

Application No.: 10/722,558

Docket No.: 20140-00310-US1

**Amendments to the Specification:**

Please amend the paragraph bridging pages 5 and 6 to read as follows:

A liner layer 22 is deposited such as by employing an HCM (Hollow Cathode Magnetron) magnetron sputter system, such as available from Applied Materials under the trade designation "Endura". See Figure 6. Typical liner materials 22 include Ta, W and Ti and nitrides thereof. A plurality of different liner materials can be used if desired. The more typical liner 22 material is Ta and even more typically alpha-phase Ta. The liner layer 22 is typically about 20 to 200 angstroms thick and were typically about 80 to about 150 angstroms thick. Processes for depositing the liner 22 are well known and need not be discussed in any detail herein. By way of example, Ta can be deposited such as by the technique disclosed in U.S. Patent 6,399,258 B1, disclosure of which is incorporated herein by reference.